



ASSEMBLY VARIANT: [No Variations]

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

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Layer	Name	Material	Thickness	Constant	Board Layer	Stack
1	Top Overlay					
2	Top Solder	Solder Resist	0.40mil	3.8		
3	Top Layer	Copper	1.40mil			
4	Dielectric 2	FR-4	8.40mil	4.2		
5	Core Layer	Copper	1.40mil			
6	Dielectric 1	FR-4	46.00mil	4.2		
7	BM Layer	Copper	1.40mil			
8	Dielectric 3	FR-4	8.40mil	4.2		
9	Bottom Layer	Copper	1.40mil			
10	Bottom Solder	Solder Resist	0.40mil	3.8		
11	Bottom Overlay					



TEXAS
INSTRUMENTS

LP-MSPHOLI 306

Public Release

FILE NAME:

ENGINEER:

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SCALE: 1.00

LAYOUT BY:

Johnson He

	ALUM DESIGNER: V
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